

Project: 2.47 inch Round DSI Screen 480x480 with CTP

Layer: **Top Overlay**

Gerber: **.GTO**

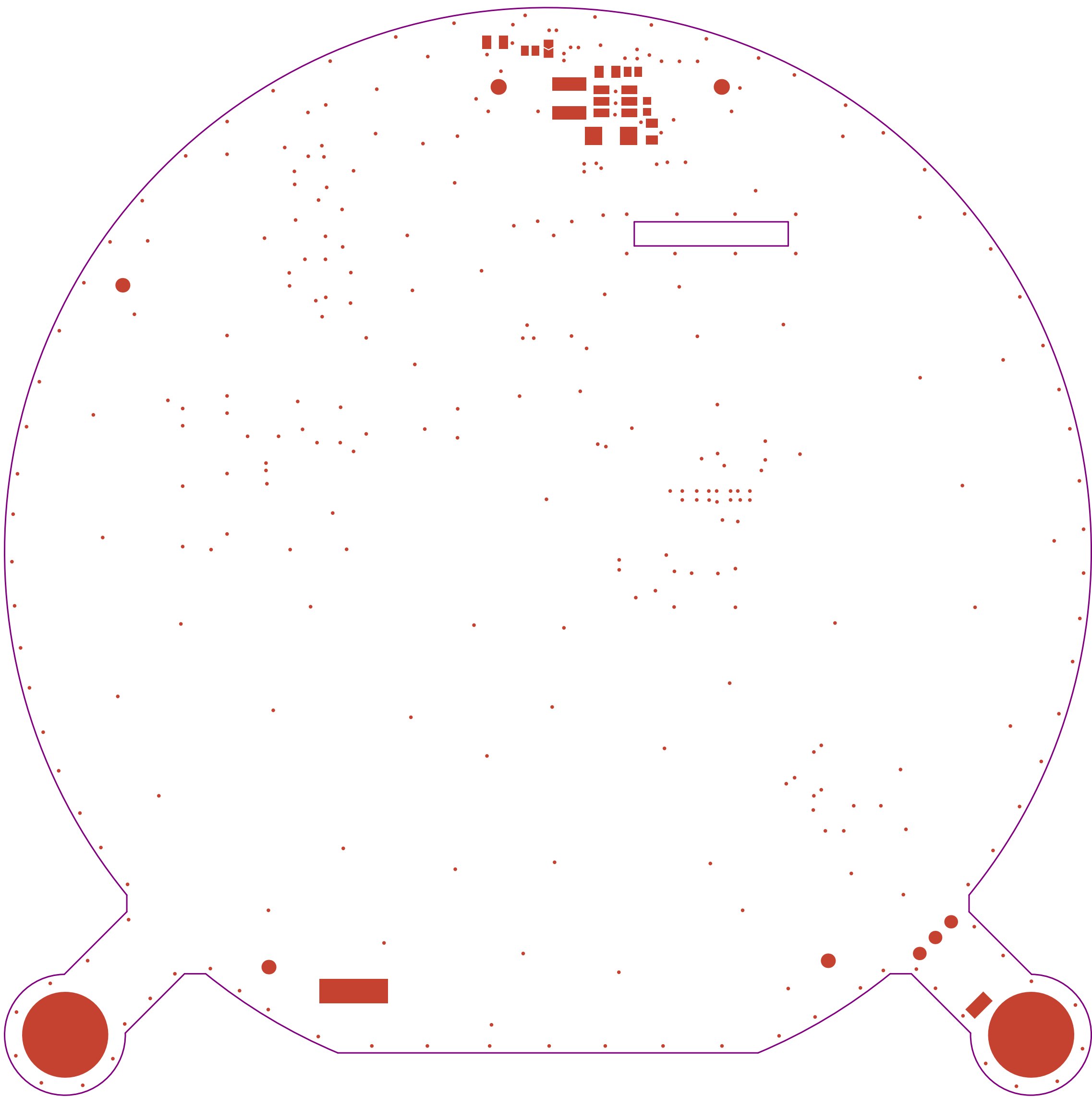
Variant: [No Variations]

MB1835

Date: 14 Mar 2023

Rev: B





Project: 2.47 inch Round DSI Screen 480x480 with CTP

Layer: **Top Solder**

Gerber: **.GTS**

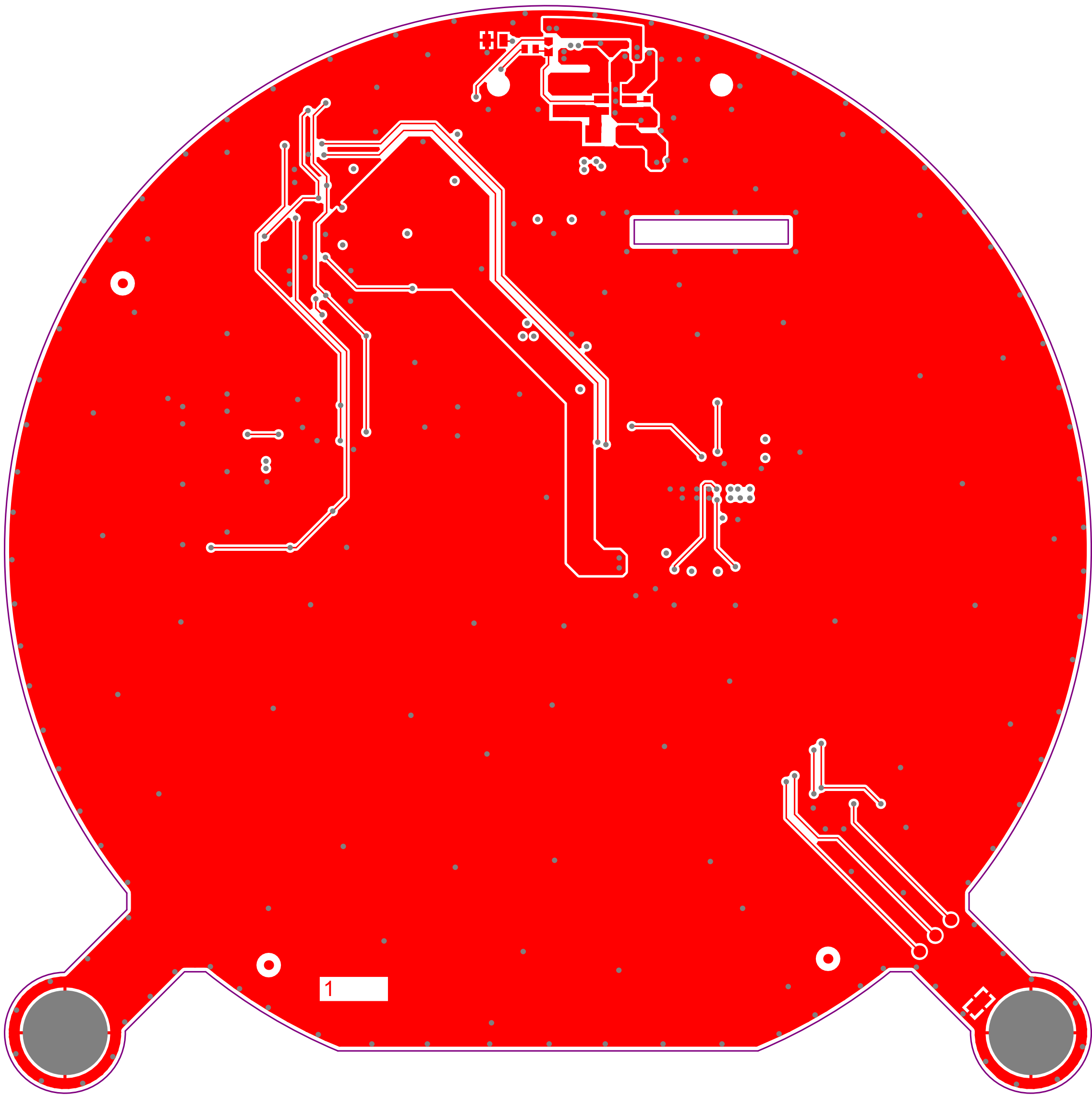
Variant: [No Variations]

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Project: 2.47 inch Round DSI Screen 480x480 with CTP

Layer: **Top Layer**

Gerber: **.GTL**

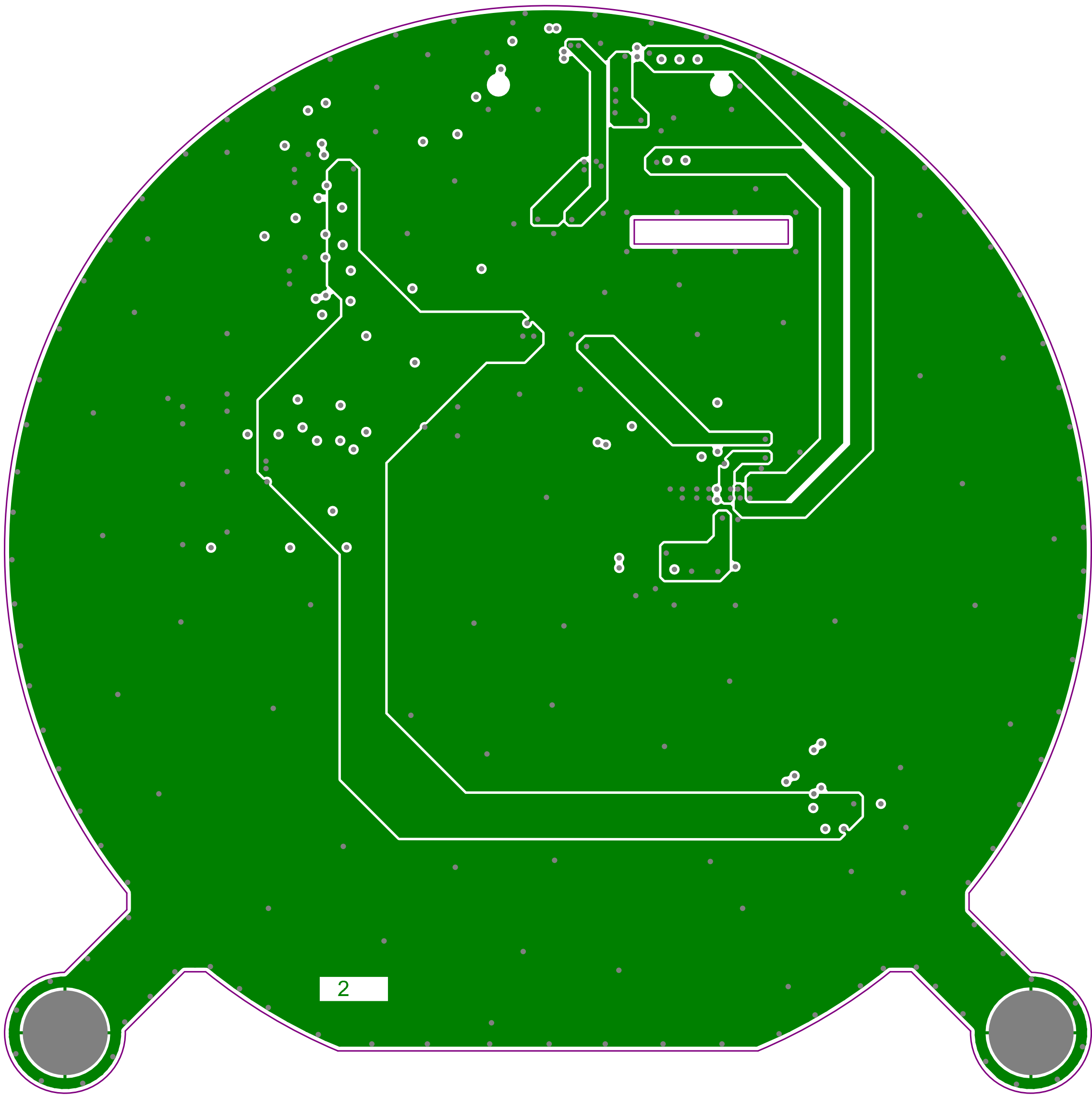
Variant: [No Variations]

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Layer: **Signal Layer 1**

Gerber: **.G1**

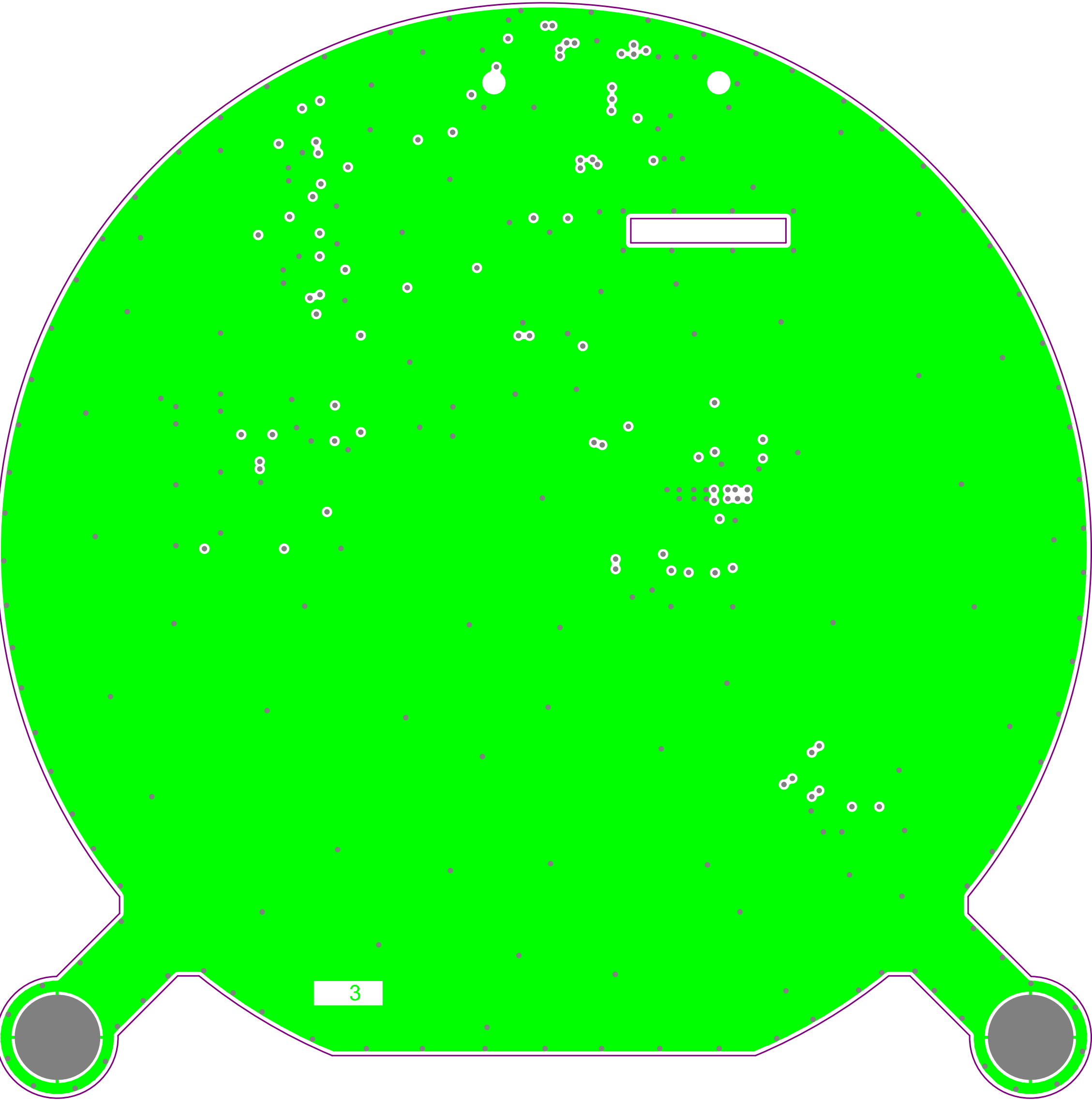
Variant: [No Variations]

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Layer: **Signal Layer 2**

Gerber: **.G2**

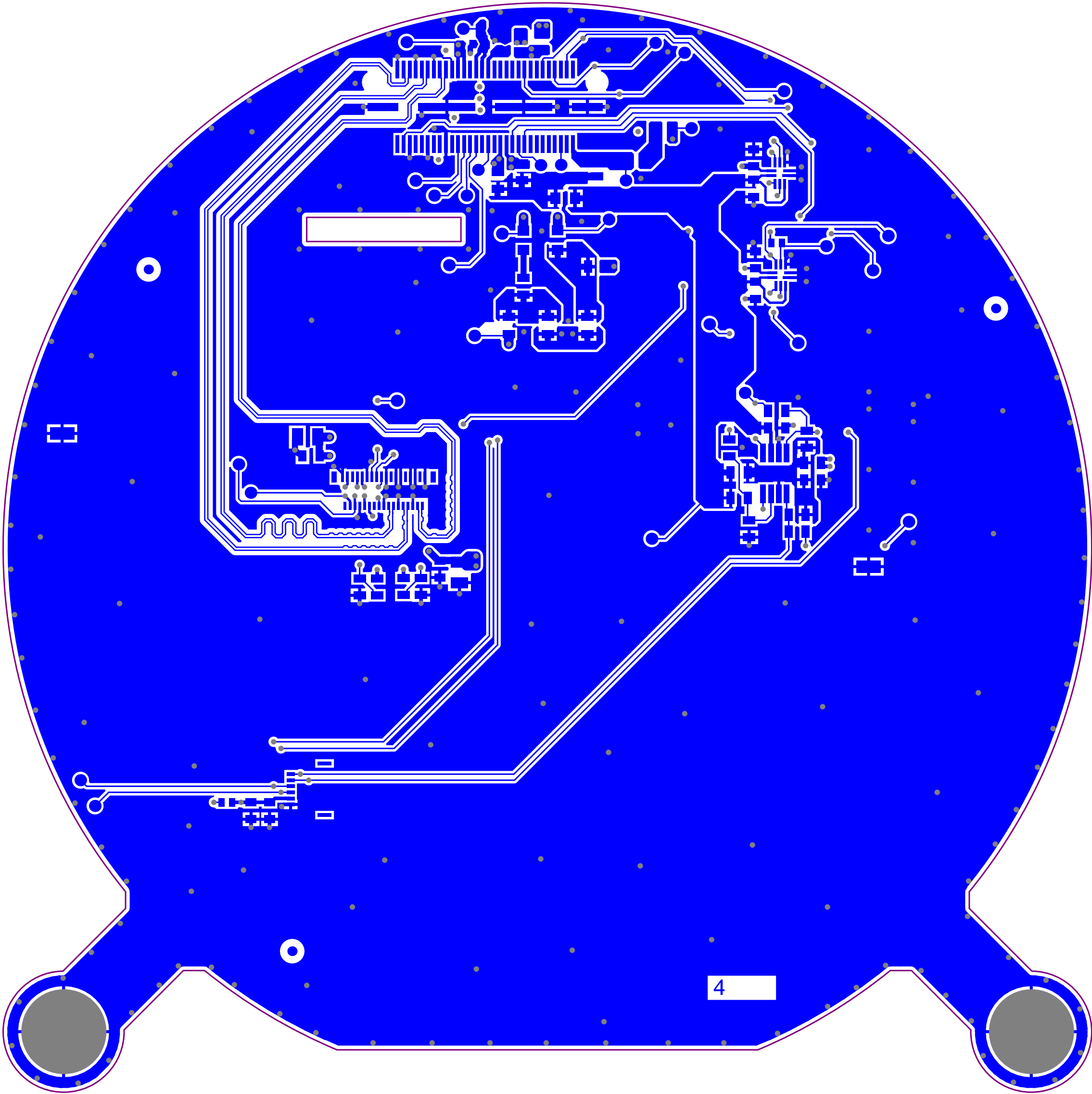
Variant: [No Variations]

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Project: 2.47 inch Round DSI Screen 480x480 with CTP

Layer: Bottom Layer

Gerber:.GBL

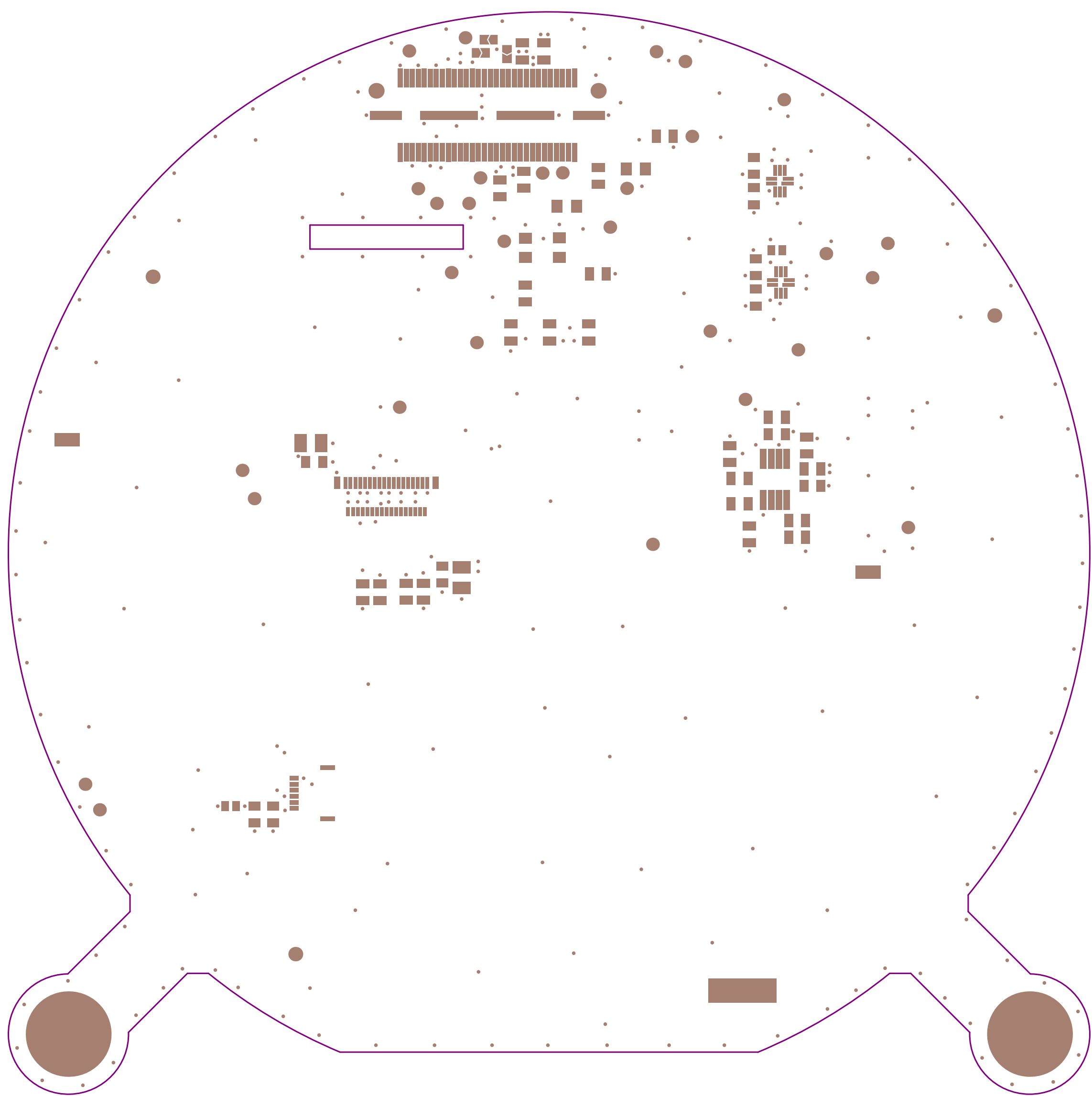
Variant: [No Variations]

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Layer: Bottom Solder

Gerber:.GBS

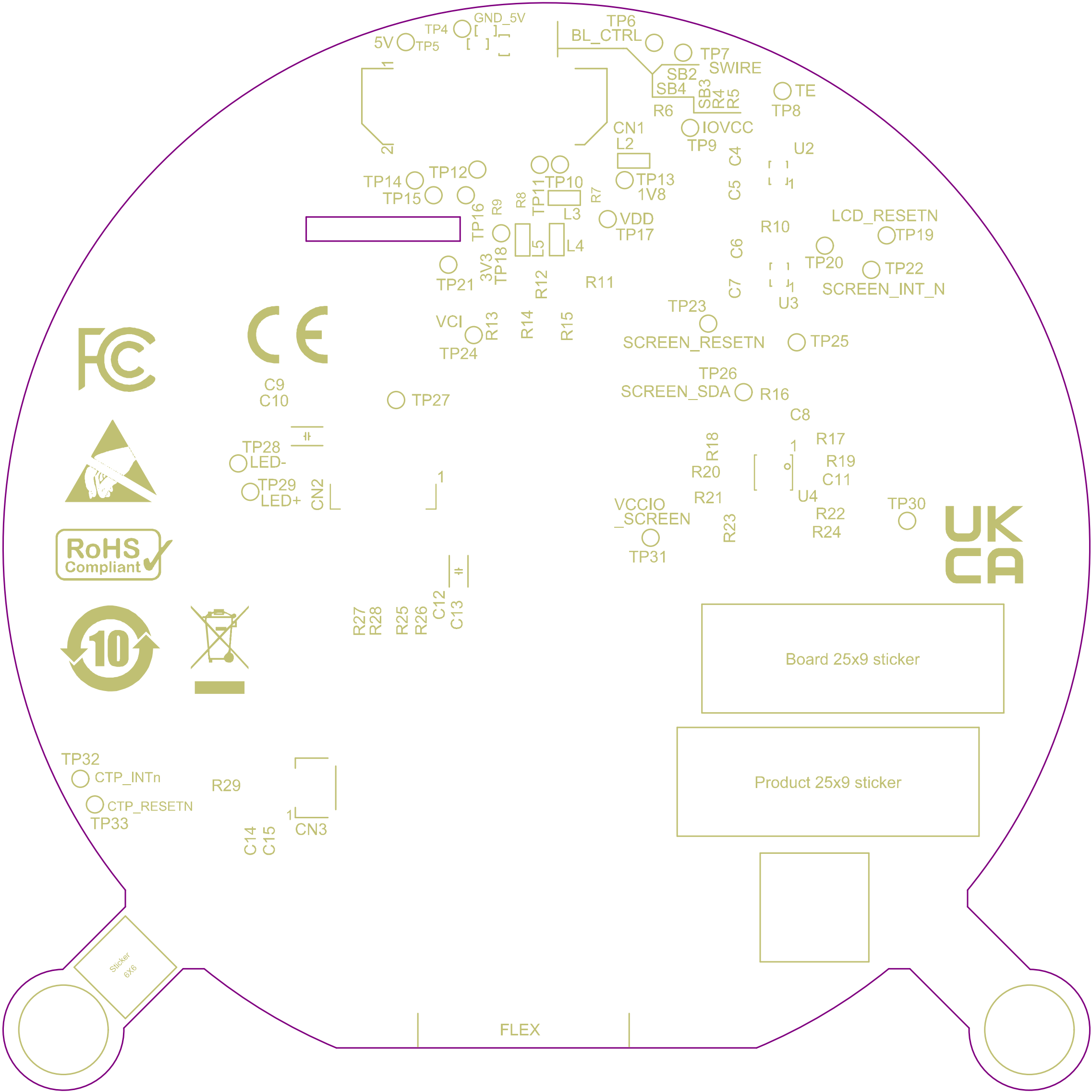
Variant: [No Variations]


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Layer: Bottom Overlay	Gerber:..GBO	
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« THE COMPONENTS WITH PLATED THROUGH HOLE (PTH) MAY BE WELDED (CABLED) IN "PIN-IN-PASTE" MODE (IF NECESSARY) »

PCB SPECIFICATIONS :

- A. MATERIAL :

B. MATERIAL FAMILY :

C. SOLDERMASK COLOR :

D. SILKSCREEN COLOR :

E. SURFACE FINISH :

F. IMPEDANCE CONTROL :

G. THROUGH VIA :

H. STACK-UP :
- FR-4

N/A

☐ GREEN

☒ WHITE

☒ ENIG

☐ HASL

☐ NO

☐ WHITE

☐ YELLOW

☐ IMMERSION SILVER

☐ HASL (PB-FREE)

☒ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

☐ RED

☐ BLACK

☐ IMMERSION TIN

☐ GOLDEN FINGER

☒ Blue ink PANTONE 2955

☐ Blue ink PANTONE 2955
- ☐ TG-170

☒ TG-150

☐ TG-140
- PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.

PLUG MATERIAL : ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

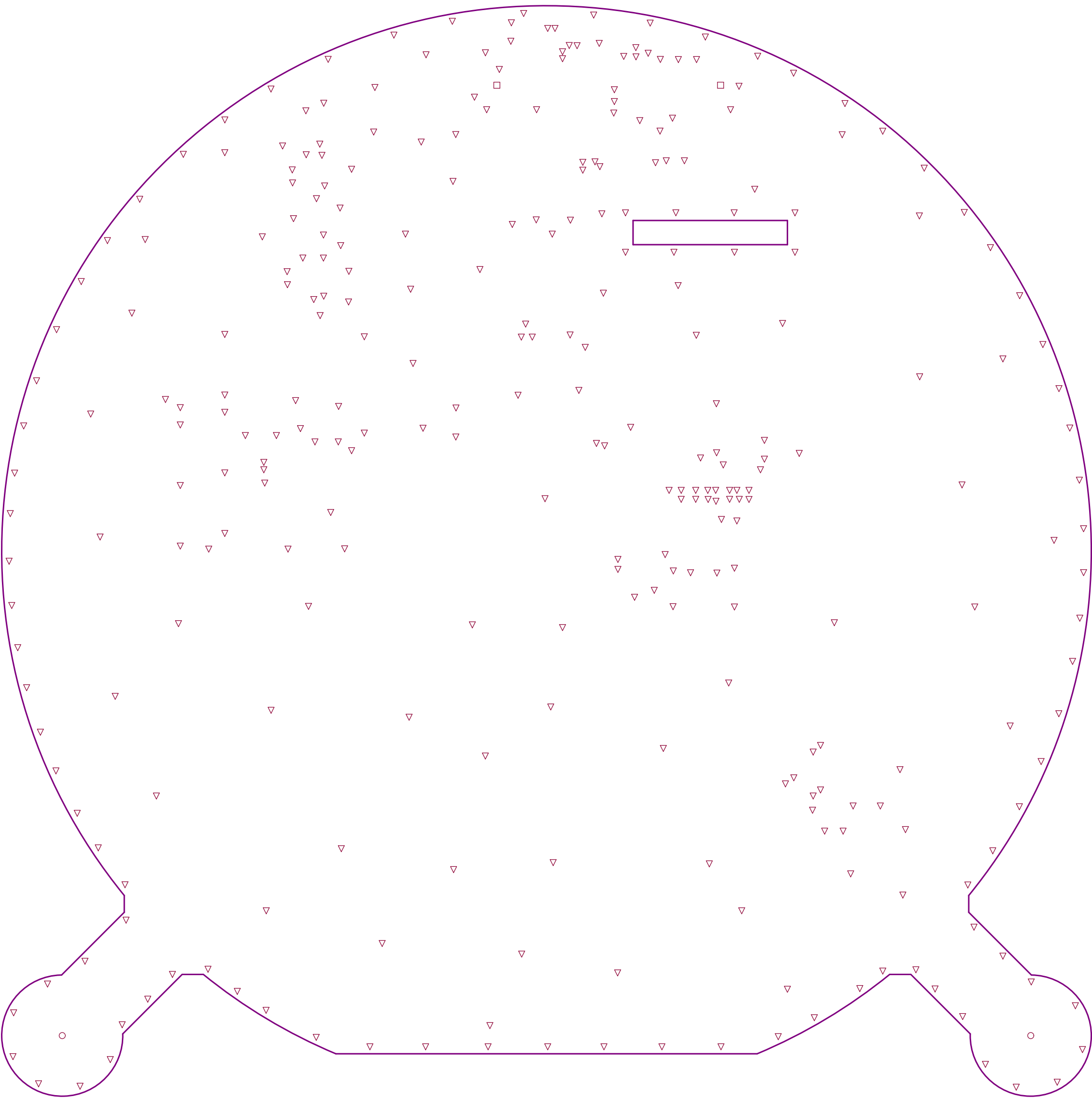
PCB : TYPE 3

ASPECT-RATIO, AXE Z :

To 6:1
LEVEL "A"

MINIMUM PARAMETERS

DEFAULT
TRACKS : 0.104mm
GAPS : 0.120mm



Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0,015mm	3.5	
1	Top Layer		0,035mm		
	Dielectric 1	PP-IT-180A	0,095mm	4.25	
2	Signal Layer 1		0,035mm		
	Dielectric 2	FR4	1,129mm	4.25	
3	Signal Layer 2		0,035mm		
	Dielectric 3	PP-IT-180A	0,095mm	4.25	
4	Bottom Layer		0,035mm		
	Bottom Solder	Solder Resist	0,015mm	3.5	
	Bottom Overlay				

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Hole Length	Routed Path Length
▽	303	0,200mm (7,87mil)	PTH	Round	Top Layer - Bottom Layer	Via	-	-
□	2	1,100mm (43,31mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-	-
○	2	3,500mm (137,79mil)	PTH	Round	Top Layer - Bottom Layer	Pad	-	-
	307 Total							

Project: 2.47 inch Round DSI Screen 480x480 with CTP

Layer: Drill Drawing

Gerber: .DRL

Variant: [No Variations]

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